

#### **General Description**

The WSM320N04G is the highest performance trench N-Ch MOSFET with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications . The WSM320N04G meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

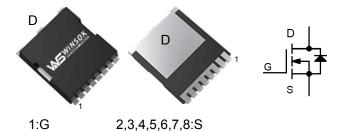
#### **Product Summery**

BVDSS	RDSON	ID
40V	1.2mΩ	320A

### **Applications**

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

#### **TOLL Pin Configuration**



#### **Absolute Maximum Ratings**

Symbol	Parameter Rating		Units
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,7</sup>	320	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,7</sup>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,7</sup> 192	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup> 900		А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	980	mJ
I <sub>AS</sub>	Avalanche Current 70		Α
P <b></b> _@T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup> 250		W
T <sub>STG</sub>	Storage Temperature Range -55 to 175		$^{\circ}$
TJ	Operating Junction Temperature Range -55 to 175		$^{\circ}$

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> 55		55	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		0.6	°C/W



### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.050		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =25A		1.2	1.5	mΩ
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =20A		1.7	2.5	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> . In =250uA	1.2	1.7	2.6	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	V <sub>GS</sub> -V <sub>DS</sub> , I <sub>D</sub> -250uA		-6.94		mV/℃
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =40V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	uA
IDSS	Diam-Source Leakage Current	$V_{DS}$ =40V , $V_{GS}$ =0V , $T_J$ =55 $^{\circ}$ C			10	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm 20V$ , $V_{DS}$ = $0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =50A		160		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.0		Ω
$Q_{g}$	Total Gate Charge (10V)			130		
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =10V , I <sub>D</sub> =25A		43		nC
$Q_gd$	Gate-Drain Charge			83		
T <sub>d(on)</sub>	Turn-On Delay Time			30		
Tr	Rise Time	V <sub>DD</sub> =20V , V <sub>GEN</sub> =4.5V ,		115		1
T <sub>d(off)</sub>	Turn-Off Delay Time	$R_G=2.7\Omega$ , $I_D=1A$ .		95		ns
T <sub>f</sub>	Fall Time			80		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		8100		
C <sub>oss</sub>	Output Capacitance			1200		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			800		

#### **Guaranteed Avalanche Characteristics**

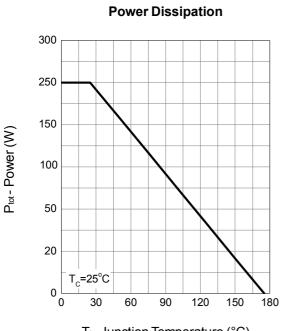
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =20V , L=0.5mH , I <sub>AS</sub> =70A	500			mJ

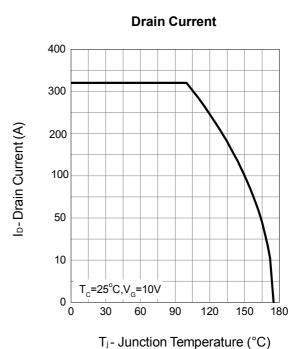
#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	−V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			320	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>				900	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =30A , T <sub>J</sub> =25℃			1.2	V

- 1 .The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec . 2 .The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =20V, $V_{GS}$ =10V,L=0.5mH, $I_{AS}$ =70A
- 4. The power dissipation is limited by 150 ℃ junction temperature 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.
- 7. Package limitation current is 100A.

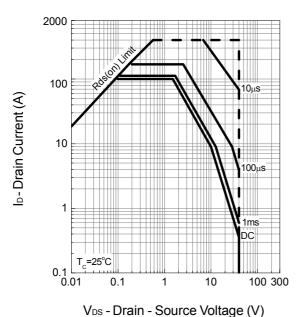




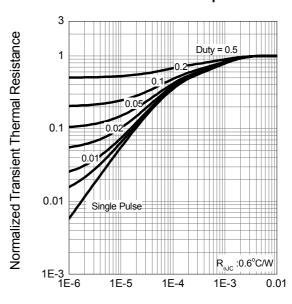


T<sub>j</sub>-Junction Temperature (°C)



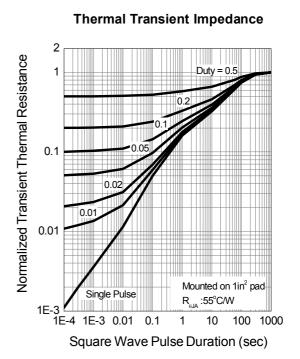


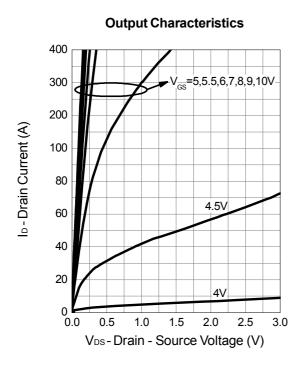
#### **Thermal Transient Impedance**

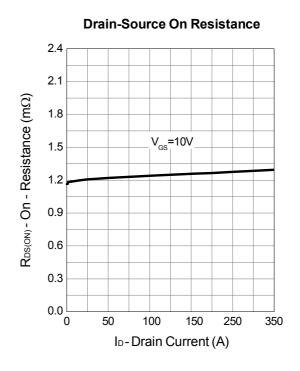


Square Wave Pulse Duration (sec)



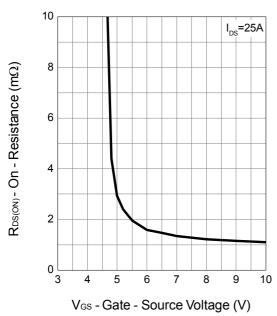




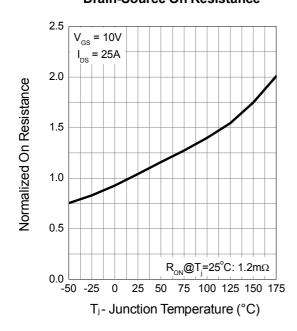




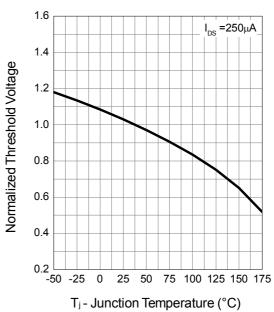
# Gate-Source On Resistance



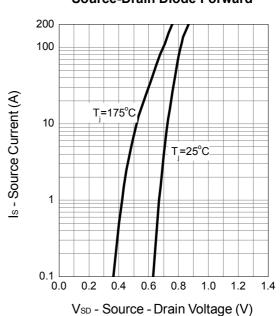
### Drain-Source On Resistance



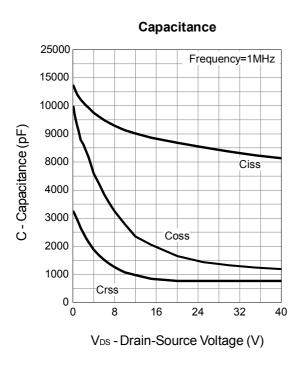
### **Gate Threshold Voltage**

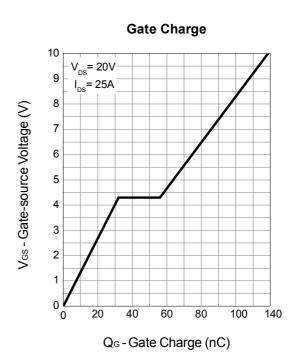


#### Source-Drain Diode Forward

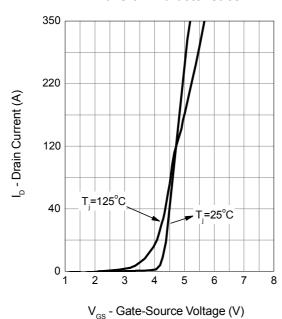








#### **Transfer Characteristics**





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